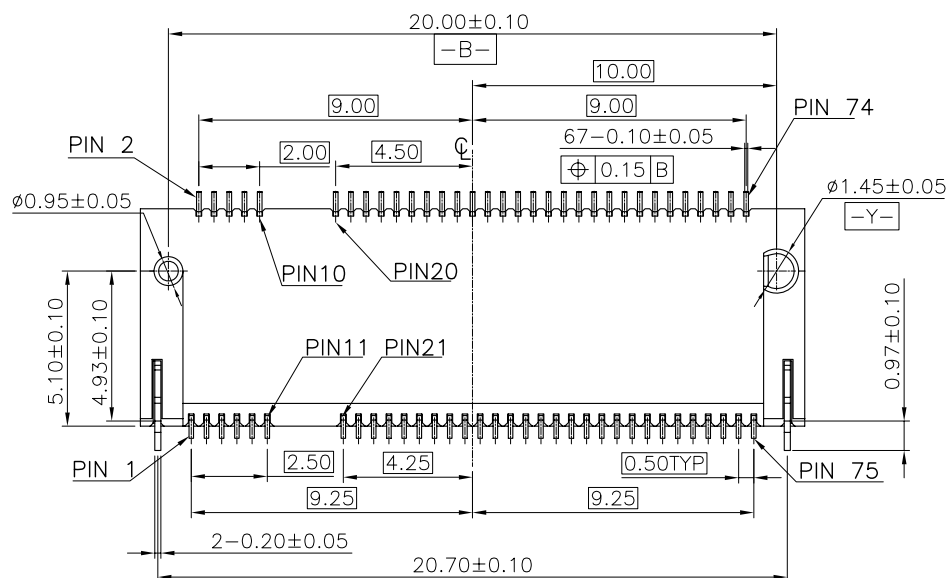
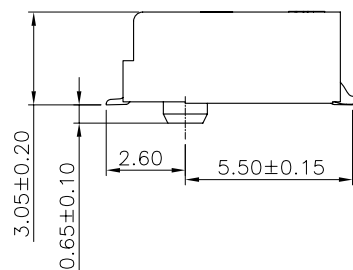
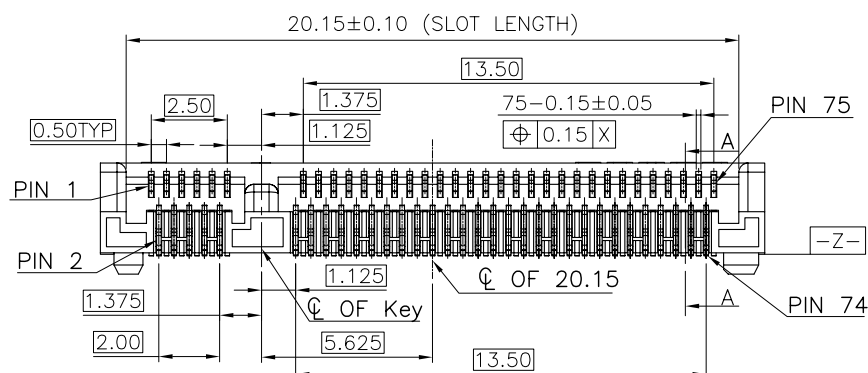
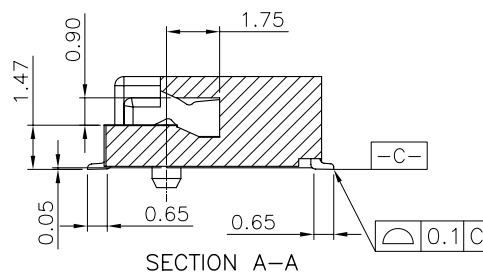
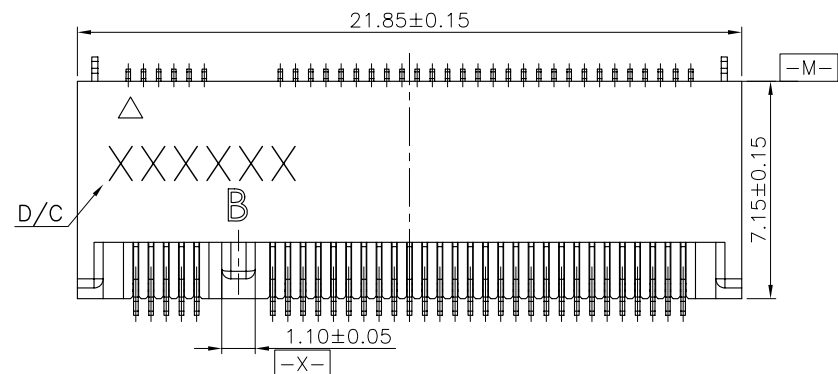




- NOTES:

1. MATERIAL SPECIFICATION:

- 1-1. HOUSING: LCP+40%GF, UL94V-0, COLOR: BLACK.

- 1-2. CONTACT: COPPER ALLOY.

- 1-3. SMT TAB: COPPER ALLOY.

2. PLATING SPECIFICATION:

- 2-1. CONTACT:

- 50μ" MIN. NICKEL UNDER PLATING OVER ALL.

- SOU MIN. NICKEL UNDER PLATING
G/F PLATING ON SOLDER AREA.

- GOLD PLATING ON CONTACT AREA:SEE TABLE

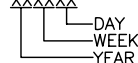
- 2-2. SMT TAB:

- 50u" MIN. NICKEL UNDER PLATING OVER ALL .

- 80u" MIN. MATTE TIN PLATING ON SOLDER AREA.

3. HF COMPLIANT,ROHS COMPLIANT.

4. DATE CODE: XXXXXX



- ### 5. MECHANICAL PERFORMANCE:

- 5-1. DURABILITY: SEE TABLE

6. ELECTRICAL PERFORMANCE:

- 6-1. CURRENT: 0.5A PER PIN.

- 6-2. LLCR: INITIAL 55mΩ MAX. : FINAL Δ LLCR=20mΩ MAX..

7. IR REFLOW:

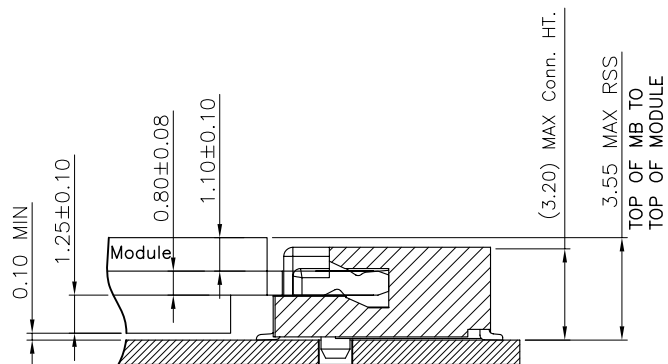
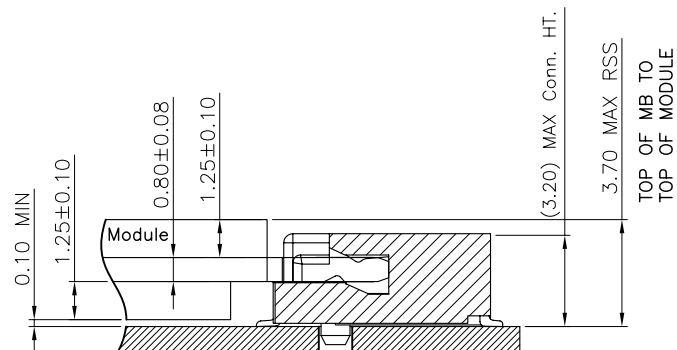
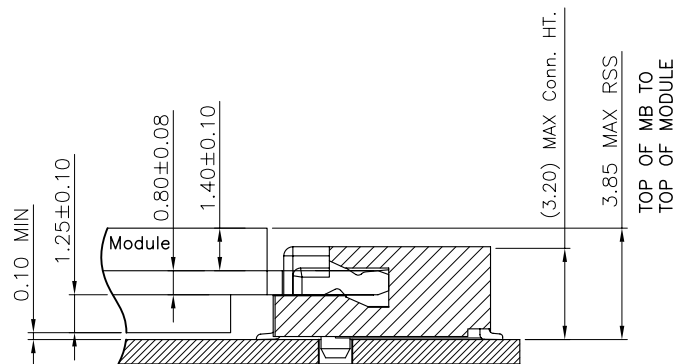
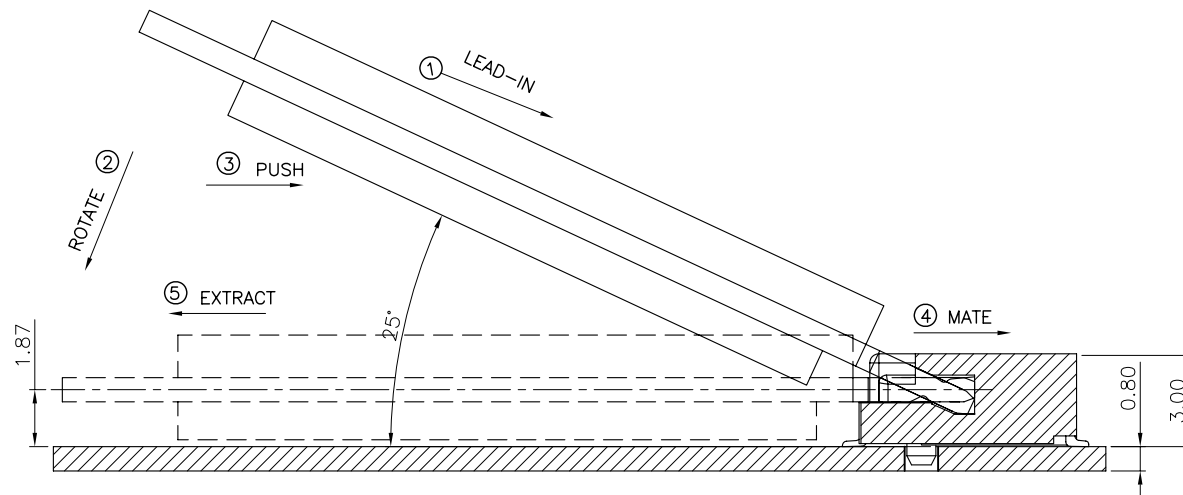
- THE TEMPERATURE SHALL BE $260 \pm 5^{\circ}\text{C}$ MAINTAINING 10 ± 1 SECONDS.



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TOLERANCE:		DRAWN BY : 陈一鸣	DATE : 2014-02-23	PART NAME: 0.5Pitch 67pin M.2 H3.2(KEY B)	
X.X ±0.30 X.XX ±0.25 X.XXX ±0.15 X.* ±2* X.X* ±0.5*				PART NO.	HYCW11B-05NGFF-320B
 UNIT: mm [inch]		CHECKED BY: 马跃	DATE : 2014-02-23	MOLD NO.	
		APPROVED BY:	DATE :	DRAW NO:	HYC-1802320912
SCALE:1:1	SIZE: A4	邱敏	2014-02-23	SHEET NO.	1 OF 1

Assembly stack height schematic diagram

Stack-up Top Mount Double Sided Module
for 1.20 max top-side component heightStack-up Top Mount Double Sided Module
for 1.35 max top-side component heightStack-up Top Mount Double Sided Module
for 1.5 max top-side component heightHOW TO MATE AND EXTRACT
=====

MATE: ① → ④

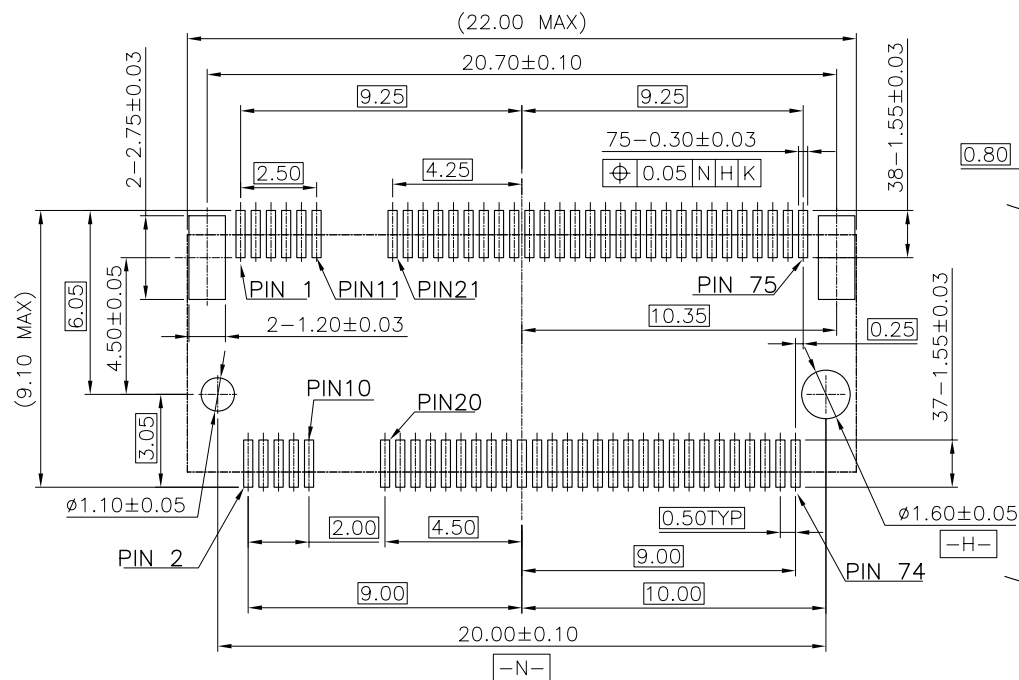
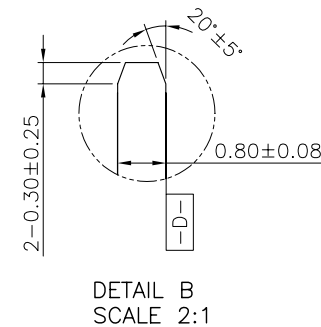
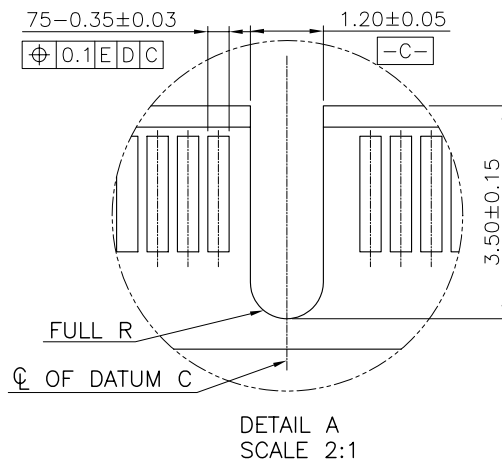
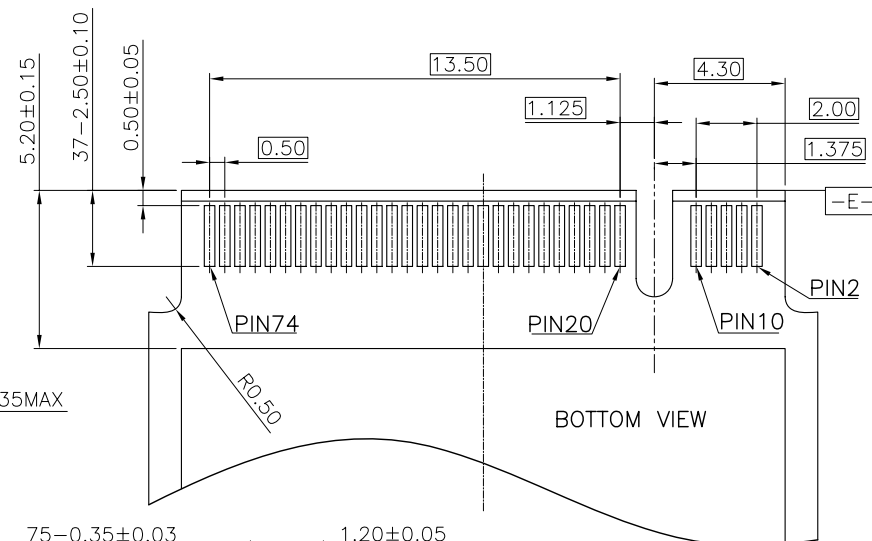
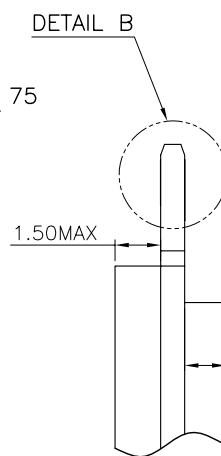
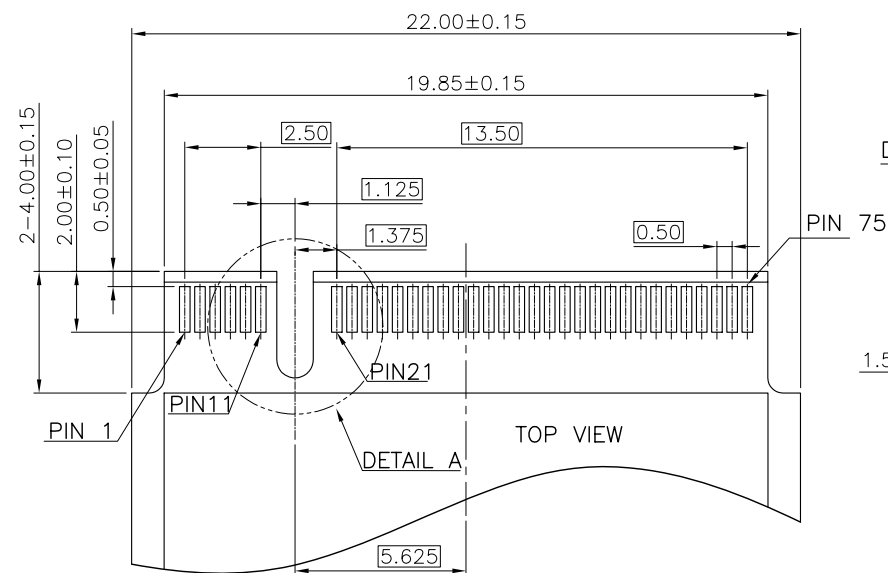
EXTRACT: ⑤

NOTE: Mating force will generate from step 3 to step 4.



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TOLERANCE: X.X ±0.30 X.XX ±0.25 X.XXX ±0.15 X' ±2" X.X' ±0.5"	DRAWN BY : 陈一鸣	DATE : 2014-02-23	PART NAME: 0.5Pitch 67pin M.2 H3.2(KEY B)	
	CHECKED BY: 马跃	DATE : 2014-02-23	PART NO.	HYCW11B-05NGFF-320B
	APPROVED BY: 邱敏	DATE : 2014-02-23	MOLD NO.	
			DRAW NO:	HYC-1802320912
SCALE:1:1	SIZE: A4		SHEET NO.	1 OF 1

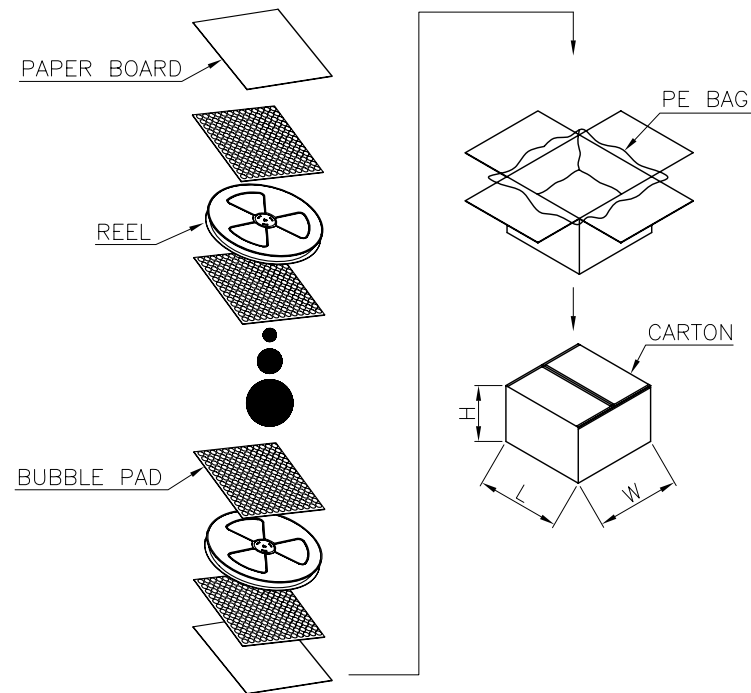
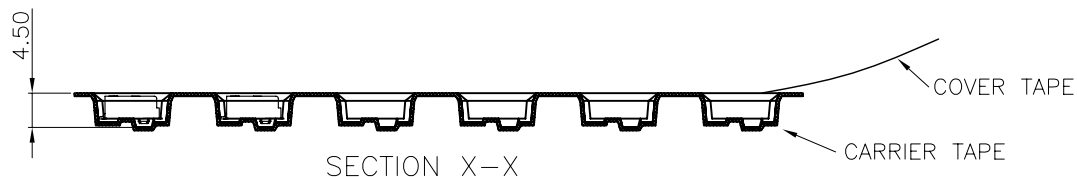
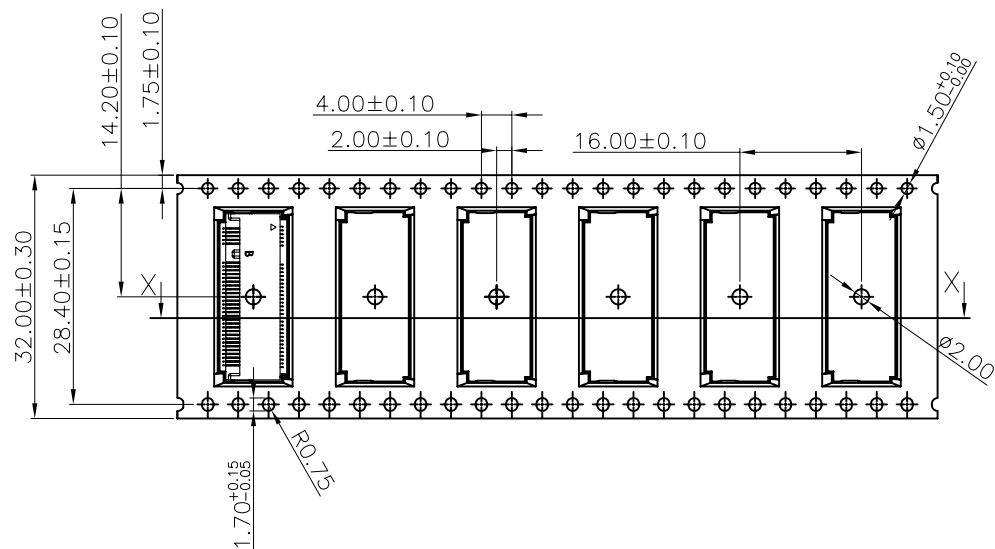
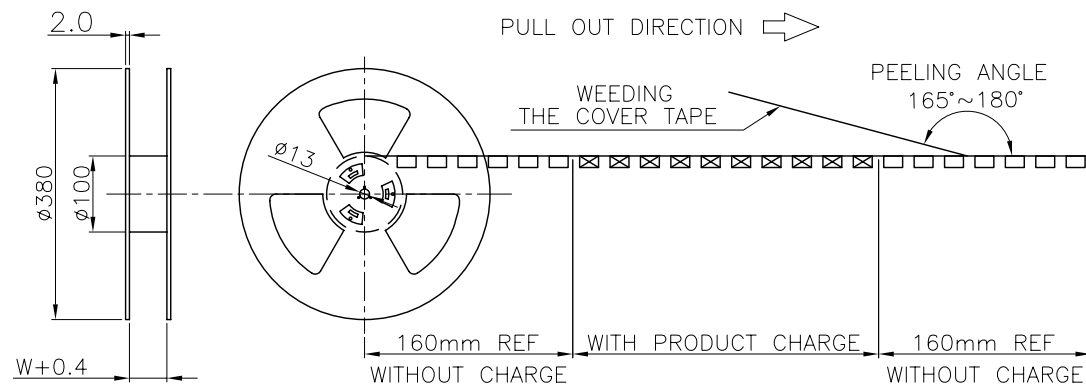


RECOMMENDED PCB LAYOUT(TOP VIEW)
DEFAULT TOLERANCE ±0.05MM



深圳市华宇创精密电子有限公司

TOLERANCE: X.X ±0.30 X.XX ±0.25 X.XXX ±0.15 X' ±2" X.X' ±0.5"	DRAWN BY : 陈一鸣	DATE : 2014-02-23	PART NAME: 0.5Pitch 67pin M.2 H3.2(KEY B)
	CHECKED BY: 马跃	DATE : 2014-02-23	PART NO. HYCW11B-05NGFF-320B
	APPROVED BY: 邱敏	DATE : 2014-02-23	MOLD NO.
UNIT: mm [inch] SCALE:1:1 SIZE: A4			DRAW NO: HYC-1802320912
			SHEET NO. 1 OF 1



1200	9600
PCS/REEL	PCS/CARTON

 深圳市华宇创精密电子有限公司				
TOLERANCE: X.X ±0.30 X.XX ±0.25 X.XXX ±0.15 X." ±2" X.X" ±0.5"   UNIT: mm [inch] SCALE: 1:1 SIZE: A4	DRAWN BY :	DATE :	PART NAME:	
	陈一鸣	2014-02-23	包装图	
	CHECKED BY:	DATE :	PART NO.	
	马跃	2014-02-23	MOLD NO.	
	APPROVED BY:	DATE :	DRAW NO:	
	邱敏	2014-02-23	SHEET NO.	1 OF 1

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[2](#) [1-1888321-3](#) [UPFS-4M08-00C6](#) [10137846-0010LF](#) [52370-2670](#) [171224-1013](#) [10031567-001C-TRLF](#)